

**PRODUCT SPECIFICATION**

**6252B-SR**

**Wi-Fi Dual-band 2x2 11ax + Bluetooth 5.2**

**Combo Module**

**Version:v1.2**



## 6252B-SR Module Datasheet

Ordering Information	Part NO.	Description
	FG6252BSRX-00	RTL8852BS-CG,a/b/g/n/ac/ax,Wi-Fi+BT5.2,2T2R,SDIO+UAR T, 2 Antenna ,no shielding
	FG6252BSRX-01	RTL8852BS-CG,a/b/g/n/ac/ax,Wi-Fi+BT5.2,2T2R,SDIO+UAR T, 3 Antenna ,no shielding

Customer: \_\_\_\_\_

Customer P/N: \_\_\_\_\_

Signature: \_\_\_\_\_

Date: \_\_\_\_\_

Office: 14th floor, Block B, phoenix zhigu, Xixiang Street, Baoan District, Shenzhen

Factory: NO.8, Litong RD., Liuyang Economic & Technical Development Zone, Changsha, CHINA

TEL:+86-755-2955-8186

Website:www.fn-link.com

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### Revision History

Version	Date	Contents of Revision Change	Prepared	Checked	Approved
V1.0	2021/08/27	Initial Release	FC	Lgp	Szs
V1.1	2021/7/30	Modify DBDC to DBSC	FC	LXY	QJP
V1.2	2021/11/5	Update the specification format	FC	LXY	QJP

# 1. General Description

## 1.1 Introduction

FN-Link Technology would like to announce a low-cost and low-power consumption module which has all of the Wi-Fi functionalities. It is a highly-integrated IEEE 802.11 a/b/g/n/ac/ax MAC/Baseband/RF WLAN single chip. For Wireless LAN operation. The integrated module provides SDIO interface for Wi-Fi. The module provides simple legacy and 20MHz/40MHz/80MHz co-existence mechanism to ensure backward and network compatibility.

The wireless module complies with IEEE 802.11 a/b/g/n/ac/ax 2x2 MIMO standard and the speed can achieve up to 1201Mbps with dual stream in 802.11ax. The integrated module provides SDIO interface for Wi-Fi, UART / PCM interface for Bluetooth.

This combo module is a total solution for a combination of Wi-Fi and Bluetooth V5.2 technologies. The module is specifically developed for all portable devices.

## 1.2 Description

Model Name	6252B-SR
Product Description	Support Wi-Fi/Bluetooth functionalities
Dimension	L x W x H: 15 x 13 x 1.8 mm
Wi-Fi Interface	Support SDIO V1.0/V2.0/V3.0
BT Interface	UART / PCM
OS supported	Android /Linux/iOS /WIN10
Operating temperature	0°C to 70°C
Storage temperature	-40°C to 85°C

## 2. Features

### General

- Highly integrated wireless local area network (WLAN) system-on-chip (SOC) for 802.11a/b/g/n/ac/ax WLAN applications
- Supports Dual band Single concurrent (2.4G/5G).

### PHY Features

- Dual-stream spatial multiplexing up to 1201 Mbps data rate.
- Supports 20/40MHz at 2.4GHz and supports 20/40/80MHz at 5GHz
- Supports Transmit Beamforming

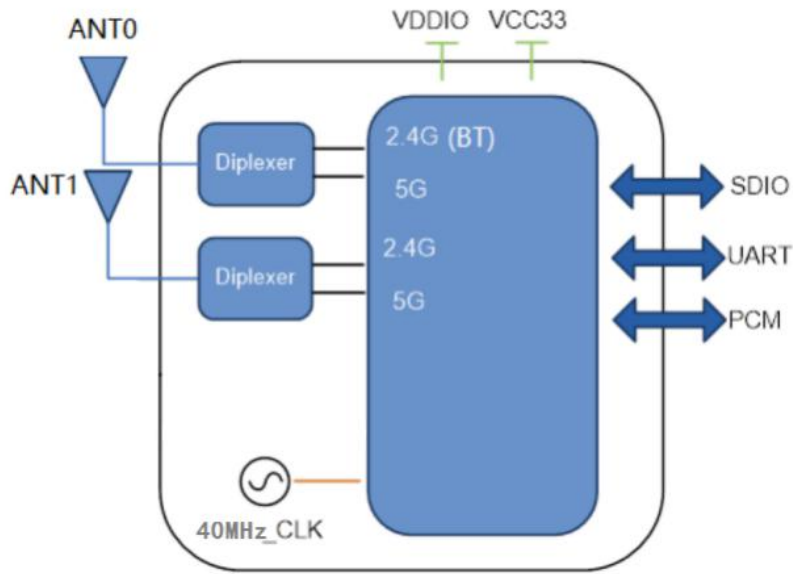
### Host Interface

- Supports low power SDIO3.0(complies with SDIO 1.1/2.0) interface for WLAN and UART/PCM interface for Bluetooth.

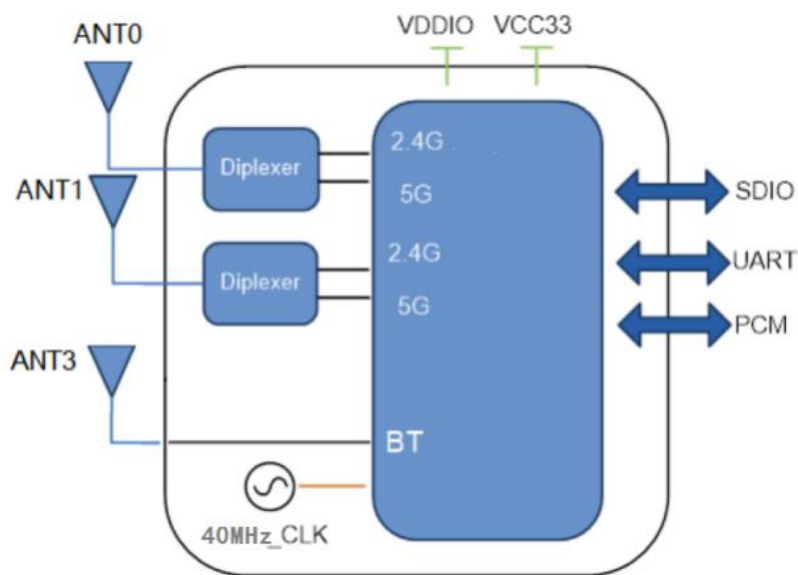
### Bluetooth Features

- Supports Bluetooth system (BT5.2 Logo Compliant)
- Supports WLAN/Bluetooth coexistence
- Compatible with Bluetooth v2.1+EDR.
- Dual Mode support: Simultaneous LE and BR/EDR
- BT host digital interface:
  - HCI UART
  - PCM for audio data

### 3. Block Diagram



--- 2 antenna version



--- 3 antenna version

## 4. General Specification

### 4.1 WI-FI 2.4GHz Specification

Feature	Description		
WLAN Standard	IEEE 802.11 b/g/n/ac/ax Wi-Fi compliant		
Frequency Range	2.400 GHz ~ 2.497 GHz (2.4 GHz ISM Band)		
Number of Channels	2.4GHz: Ch1 ~ Ch14		
Test Items	Typical Value		EVM
Output Power <sup>1</sup>	802.11b /11Mbps : 19dBm ± 2 dB		EVM ≤ -9dB
	802.11g /54Mbps : 18dBm ± 2 dB		EVM ≤ -25dB
	802.11n /MCS7 : 17dBm ± 2 dB		EVM ≤ -28dB
	802.11ac vHT20 MCS8: 16dBm ± 2 dB		EVM ≤ -30dB
	802.11ac vHT40 MCS9: 15dBm ± 2 dB		EVM ≤ -32dB
	802.11ax HE20 MCS11: 13dBm ± 2 dB		EVM ≤ -35dB
	802.11ax HE40 MCS11: 13dBm ± 2 dB		EVM ≤ -35dB
Spectrum Mask	Meet with IEEE standard		
Freq. Tolerance	± 20ppm		
SISO Receive Sensitivity (11b,20MHz) @8% PER	- 1Mbps	PER @ -94 dBm	≤-83
	- 11Mbps	PER @ -85 dBm	≤-76
SISO Receive Sensitivity (11g,20MHz) @10% PER	- 6Mbps	PER @ -90 dBm	≤-85
	- 54Mbps	PER @ -71 dBm	≤-68
SISO Receive Sensitivity (11n,20MHz) @10% PER	- MCS=0	PER @ -90 dBm	≤-85
	- MCS=7	PER @ -69 dBm	≤-67
SISO Receive Sensitivity (11n,40MHz) @10% PER	- MCS=0	PER @ -87 dBm	≤-82
	- MCS=7	PER @ -66 dBm	≤-64
SISO Receive Sensitivity (11ac,20MHz) @10% PER	- MCS=0	PER @ -90 dBm	≤ -82
	- MCS=8	PER @ -66 dBm	≤ -60
SISO Receive Sensitivity (11ac ,40MHz) @10% PER	- MCS=0	PER @ -87 dBm	≤ -79
	- MCS=9	PER @ -59 dBm	≤ -55
SISO Receive Sensitivity (11ax,20MHz) @10% PER	- MCS=0	PER @ -90 dBm	≤-74
	- MCS=11	PER @ -60 dBm	≤-52
SISO Receive Sensitivity (11ax ,40MHz) @10% PER	- MCS=0	PER @ -87 dBm	≤-71
	- MCS=11	PER @ -57 dBm	≤-49
Maximum Input Level	802.11b : -10 dBm		
	802.11g/n : -20 dBm		
Antenna Reference	Small antennas with 0~2 dBi peak gain		



## 4.2 WI-FI 5GHz Specification

Feature	Description		
WLAN Standard	IEEE 802.11a/n/ac/ax, Wi-Fi compliant		
Frequency Range	5.15 GHz ~ 5.850 GHz(5.0 GHz ISM Band)		
Test Items	Typical Value		EVM
Output Power <sup>1</sup>	802.11a /54Mbps:	18 dBm ± 2 dB	EVM ≤ -25dB
	802.11n /MCS7:	17 dBm ± 2 dB	EVM ≤ -28dB
	802.11ac vHT20 MCS8:	16 dBm ± 2 dB	EVM ≤ -30dB
	802.11ac vHT40 MCS9:	15 dBm ± 2 dB	EVM ≤ -32dB
	802.11ac vHT80 MCS9:	15 dBm ± 2 dB	EVM ≤ -32dB
	802.11ax HE20 MCS11:	13 dBm ± 2 dB	EVM ≤ -35dB
	802.11ax HE40 MCS11:	13 dBm ± 2 dB	EVM ≤ -35dB
	802.11ax HE80 MCS11:	13 dBm ± 2 dB	EVM ≤ -35dB
Spectrum Mask	Meet with IEEE standard		
Freq. Tolerance	± 20ppm		
SISO Receive Sensitivity (11a,20MHz) @10% PER	- 6Mbps	PER @ -90 dBm	≤-85
	- 54Mbps	PER @ -71 dBm	≤-68
SISO Receive Sensitivity (11n,20MHz) @10% PER	- MCS=0	PER @ -90 dBm	≤-85
	- MCS=7	PER @ -69 dBm	≤-67
SISO Receive Sensitivity (11n,40MHz) @10% PER	- MCS=0	PER @ -87 dBm	≤-82
	- MCS=7	PER @ -66 dBm	≤-64
SISO Receive Sensitivity (11ac,20MHz) @10% PER	- MCS=0, NSS1	PER @ -90 dBm	≤ -82
	- MCS=8, NSS1	PER @ -66 dBm	≤ -60
SISO Receive Sensitivity (11ac ,40MHz) @10% PER	- MCS=0, NSS1	PER @ -87 dBm	≤ -79
	- MCS=9, NSS1	PER @ -59 dBm	≤ -55
SISO Receive Sensitivity (11ac,80MHz) @10% PER	- MCS=0, NSS1	PER @ -84 dBm	≤-79
	- MCS=9, NSS1	PER @ -56 dBm	≤-54
SISO Receive Sensitivity (11ax,20MHz) @10% PER	- MCS=0	PER @ -90 dBm	≤-74
	- MCS=11	PER @ -60 dBm	≤-52
SISO Receive Sensitivity (11ax ,40MHz) @10% PER	- MCS=0	PER @ -87 dBm	≤-71
	- MCS=11	PER @ -57 dBm	≤-49
SISO Receive Sensitivity (11ax,80MHz) @10% PER	- MCS=0	PER @ -84 dBm	≤-68
	- MCS=11	PER @ -54 dBm	≤-46

Maximum Input Level	802.11a/n: -30 dBm
Antenna Reference	Small antennas with 0~2 dBi peak gain

2. 2.4G,5G output power control by firmware power by rate table, the table value must same with module target power

**15GHz(20MHz) Channel table**

<b>Band range</b>	<b>Operating Channel Numbers</b>	<b>Channel center frequencies(MHz)</b>
5180MHz~5240MHz	36	5180
	40	5200
	44	5220
	48	5240
5260MHz~5320MHz	52	5260
	56	5280
	60	5300
	64	5320
5550MHz~5700MHz	100	5500
	104	5520
	108	5540
	112	5560
	116	5580
	120	5600
	124	5620
	128	5640
	132	5660
	136	5680
	140	5700
	5745MHz~5825MHz	149
153		5765
157		5785
161		5805
165		5825

Note: The Wi-Fi RF specification data will be updated in future version.

### 4.3 Bluetooth Specification

Feature	Description		
<b>General Specification</b>			
Bluetooth Standard	Bluetooth V5.2.		
Host Interface	UART		
Antenna Reference	Small antennas with 0~2 dBi peak gain		
Frequency Band	2402 MHz ~ 2480 MHz		
Number of Channels	79 channels		
Modulation	GFSK, $\pi/4$ -DQPSK, 8-DPSK		
<b>RF Specification</b>			
	<b>Min(dBm)</b>	<b>Typical(dBm)</b>	<b>Max(dBm)</b>
Output Power (Class 1)	2	5	8
Sensitivity @ BER=0.1% for GFSK (1Mbps)		-92	
Sensitivity @ BER=0.01% for $\pi/4$ -DQPSK (2Mbps)		-86	
Sensitivity @ BER=0.01% for 8DPSK (3Mbps)		-85	
Maximum Input Level	GFSK (1Mbps):-20dBm		
	$\pi/4$ -DQPSK (2Mbps) :-20dBm		
	8DPSK (3Mbps) :-20dBm		

Note: The Bluetooth Specification will be updated in future version.

### 5. ID setting information

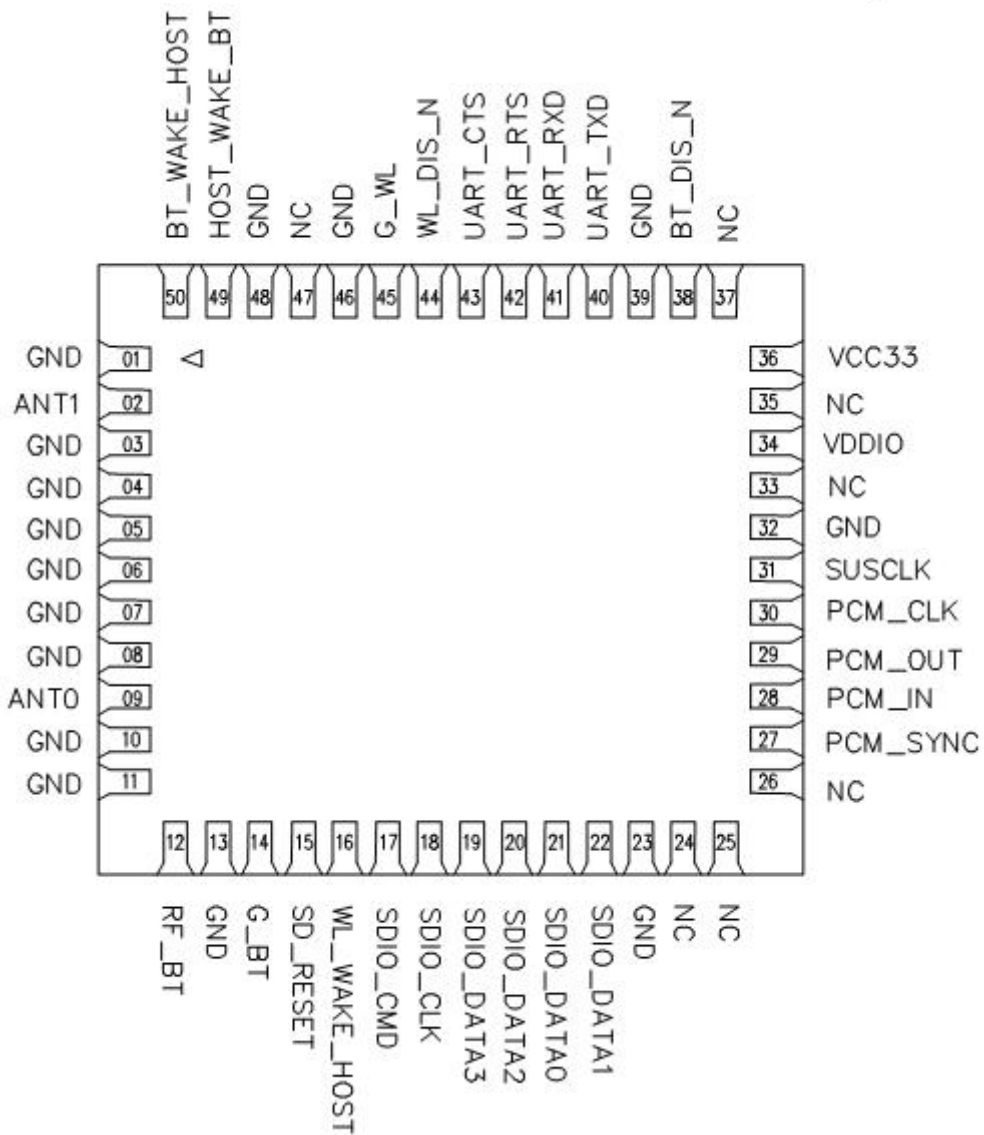
WI-FI

Vendor ID	TBD
Product ID	TBD

## 6. Pin Definition

### 6.1 Pin Outline

< TOP VIEW >



## 6.2 Pin Definition details

NO.	Name	Type	Description	Voltage
1	GND	—	Ground connections	
2	ANT1	I/O	RF I/O port chain1, dual band Wi-Fi and BT for (2ant type)	
3	GND	—	Ground connections	
4	GND	—	Ground connections	
5	GND	—	Ground connections	
6	GND	—	Ground connections	
7	GND	—	Ground connections	
8	GND	—	Ground connections	
9	ANT0	I/O	RF I/O port chain0, dual band Wi-Fi	
10	GND	—	Ground connections	
11	GND	—	Ground connections	
12	NC or BT_TRX	I/O	Reserved for BT RF I/O port, used only in 3 ANT version	
13	GND	—	Ground connections	
14	G_BT	—	GPIO5. G_BT If not used keep NC. Do not connect to GND.	VDDIO
15	SD_RESET	I	Reset Pin for SDIO interface ON: pull high; OFF: pull low Low for disable SDIO interface	VDDIO
16	WL_WAKE_HOST	O	GPIO10. WLAN to wake-up HOST	VDDIO
17	SDIO_CMD	I/O	SDIO command line	VDDIO
18	SDIO_CLK	I/O	SDIO clock line	VDDIO
19	SDIO_DATA3	I/O	SDIO data line 3	VDDIO
20	SDIO_DATA2	I/O	SDIO data line 2	VDDIO
21	SDIO_DATA0	I/O	SDIO data line 0	VDDIO
22	SDIO_DATA1	I/O	SDIO data line 1	VDDIO
23	GND	—	Ground connections	
24	NC	—	No connect	
25	NC	—	No connect	
26	NC	—	No connect	
27	PCM_SYNC	I/O	PCM sync signal	VDDIO
28	PCM_IN	I	PCM data input	VDDIO

29	PCM_OUT	O	PCM Data output	VDDIO
30	PCM_CLK	I/O	PCM clock	VDDIO
31	SUSCLK	I	External Low Power Clock input (32.768KHz) If not used keep NC	
32	GND	—	Ground connections	
33	NC	—	No connect	
34	VDDIO	P	I/O Voltage supply input 1.8V or 3.3V	1.8V or3.3V
35	NC	—	No connect	
36	VCC33	P	Main power voltage source input 3.3V	3.3V
37	NC	—	No connect	
38	BT_DIS_N	I	Enable pin for Bluetooth device ON: pull high; OFF: pull low External pull low to shut down BT	VDDIO
39	GND	—	Ground connections	
40	UART_TXD	O	Bluetooth UART interface	VDDIO
41	UART_RXD	I	Bluetooth UART interface	VDDIO
42	UART_RTS	O	Bluetooth UART interface	VDDIO
43	UART_CTS	I	Bluetooth UART interface	VDDIO
44	WL_DIS_N	—	Enable pin for WLAN Radio ON: pull high; OFF: pull low External pull low to disable WLAN Radio	VDDIO
45	G_WL	—	GPIO4, G_WL If not used keep NC. Do not pull high on this pin.	VDDIO
46	GND	—	Ground connections	
47	NC	—	No connect	
48	GND	—	Ground connections	
49	HOST_WAKE_BT	I	HOST wake-up Bluetooth device	VDDIO
50	BT_WAKE_HOST	O	Bluetooth device to wake-up HOST	VDDIO

P:POWER I:INPUT O:OUTPUT VDDIO:3.3V

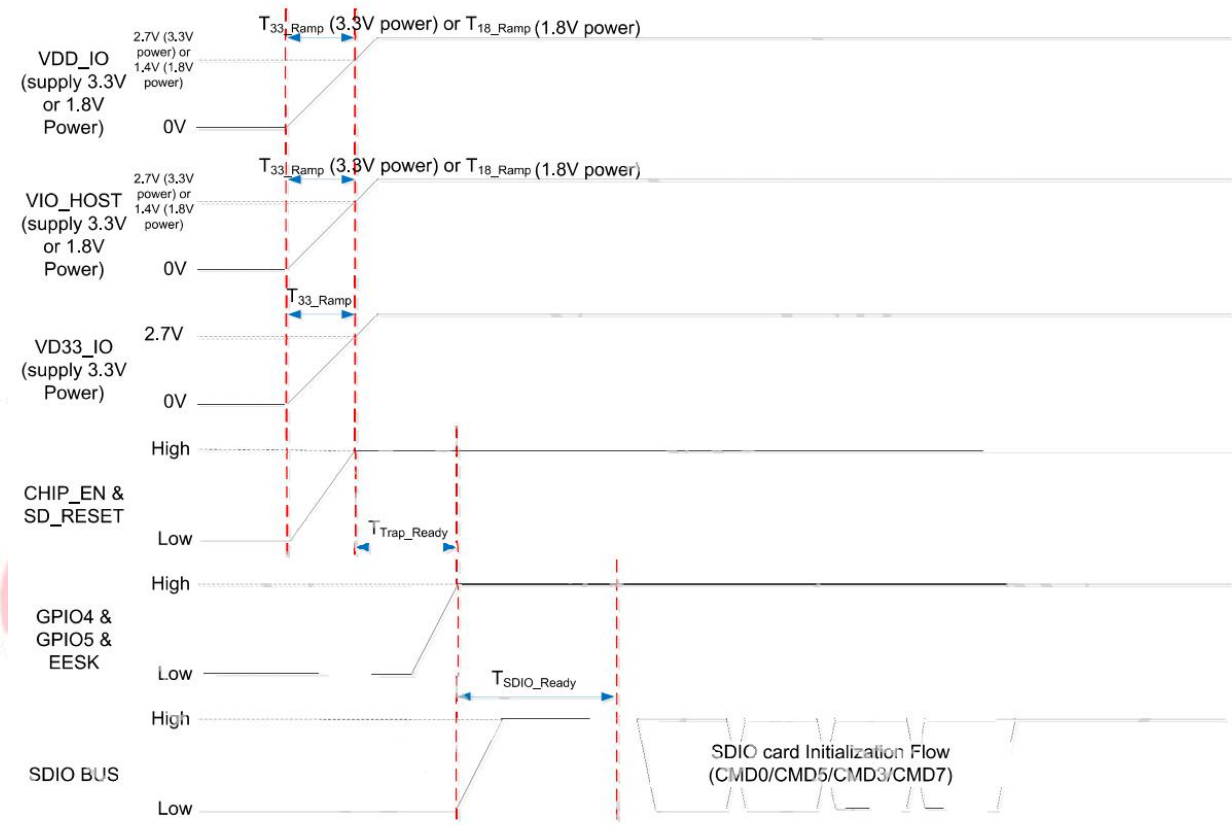
## 7. Electrical Specifications

### 7.1 Power Supply DC Characteristics

	Min.	Typ.	Max.	Unit
Operating Temperature	0	25	70	deg.C
VCC33	3.15	3.3	3.45	V
VDDIO (3.3V)	-	3.3	3.6	V
VDDIO (1.8V)	1.68	1.8	1.98	V

### 7.2 Interface Circuit time series

#### 7.2.1 Power on sequence





	Min.	Typical	Max.	Unit	Description
T18_Ramp	0.5	1.5	5	ms	The 1.8V power ramp up duration.
T33_Ramp	0.5	1.5	5	ms	The 3.3V power ramp up duration.
TTrap_Ready	400	500	X	ms	WLAN eFuse autoload. TTrap_Ready = 500ms (Typical)
TSDIO_Ready	10	20	X	ms	SDIO Not Ready Duration. In this state, the RTL8852BS may respond to commands without the ready bit being set. After the ready bit is set, the host will initiate complete card detection procedure.

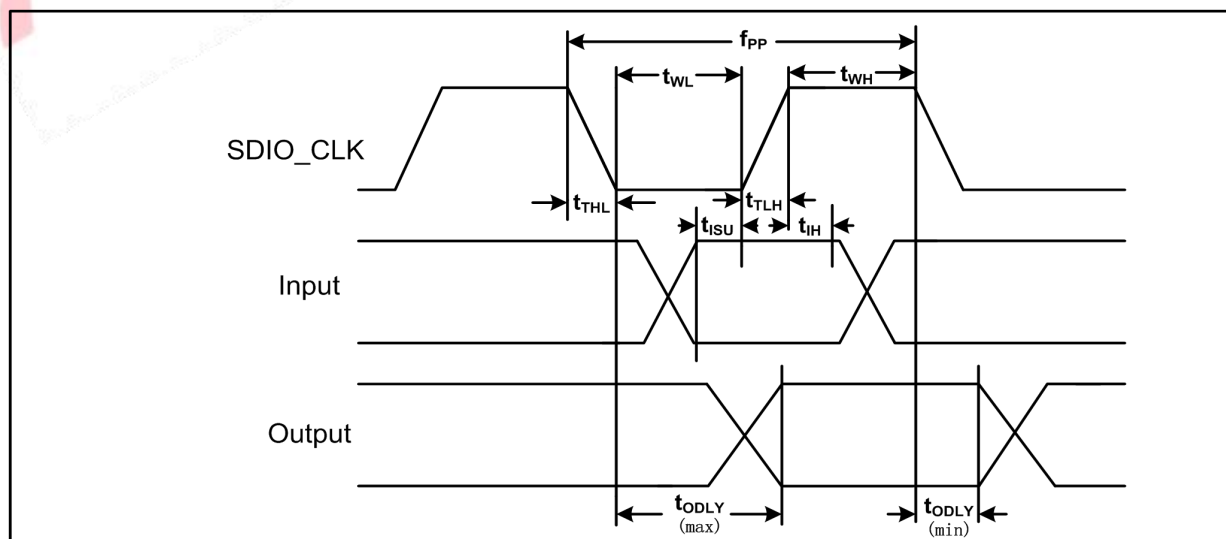
### 7.2.2 SDIO Pin Description

The module supports SDIO version 3.0 for all 1.8V 4-bit UHSI speeds: SDR50(100 Mbps), SDR104(208MHz) and DDR50(50MHz, dual rates) in addition to the 3.3V default speed(25MHz) and high speed (50 MHz). It has the ability to stop the SDIO clock and map the interrupt signal into a GPIO pin. This ‘out-of-band’ interrupt signal notifies the host when the WLAN device wants to turn on the SDIO interface. The ability to force the control of the gated clocks from within the WLAN chip is also provided.

SDIO Pin Description

SD 4-Bit Mode	
DATA0	Data Line 0
DATA1	Data Line 1 or Interrupt
DATA2	Data Line 2 or Read Wait
DATA3	Data Line 3
CLK	Clock
CMD	Command Line

### 7.2.3 SDIO Default Mode Timing Diagram

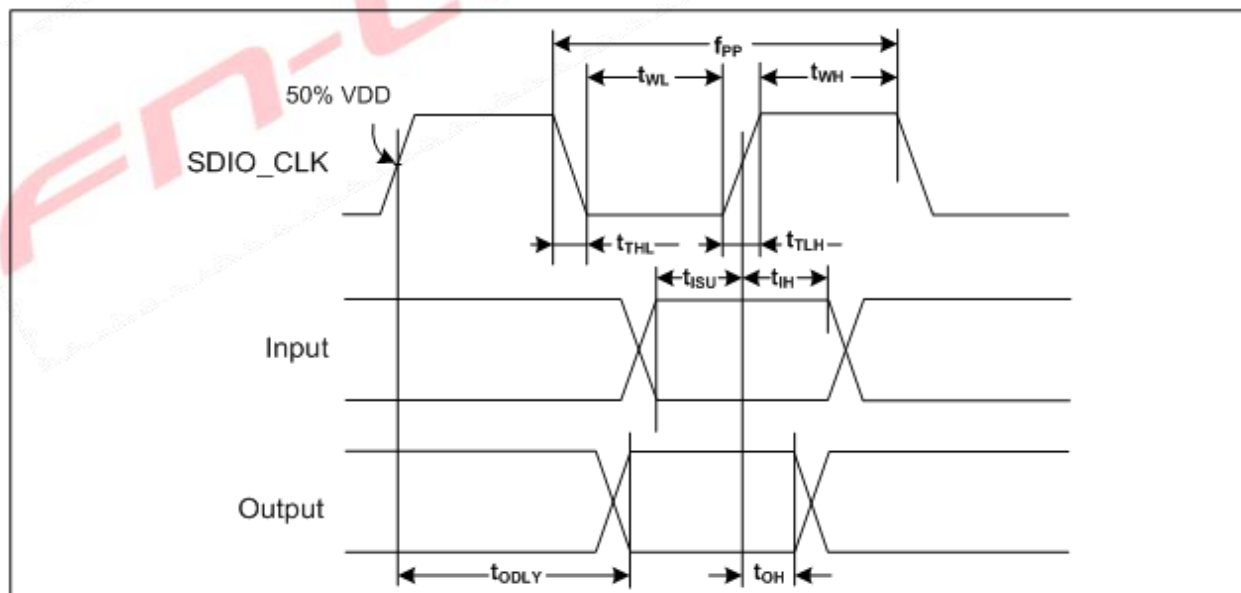




<b>Parameter</b>	<b>Symbol</b>	<b>Minimum</b>	<b>Typical</b>	<b>Maximum</b>	<b>Unit</b>
<b>SDIO CLK(All values are referred to minimum VIH and maximum VIL<sup>b</sup>)</b>					
Frequency - Data Transfer mode	fPP	0	-	25	MHz
Frequency - Identification mode	fOD	0	-	400	kHz
Clock low time	tWL	10	-	-	ns
Clock high time	tWH	10	-	-	ns
Clock rise time	tTLH	-	-	10	ns
Clock low time	tTHL	-	-	10	ns
<b>Inputs:CMD, DAT(referenced to CLK)</b>					
Input setup time	tISU	5	-	-	ns
Input hold time	tIH	5	-	-	ns
<b>Outputs:CMD, DAT(referenced to CLK)</b>					
Output delay time - Data Transfer mode	tODLY	0	-	14	ns
Output delay time - Identification mode	tODLY	0	-	50	ns

- a. Timing is based on  $CL \leq 40$  pF load on CMD and Data.
- b.  $Min(V_{ih}) = 0.7 \times V_{DDIO}$  and  $max(V_{il}) = 0.2 \times V_{DDIO}$ .

**7.2.4 SDIO High Speed Mode Timing Diagram**



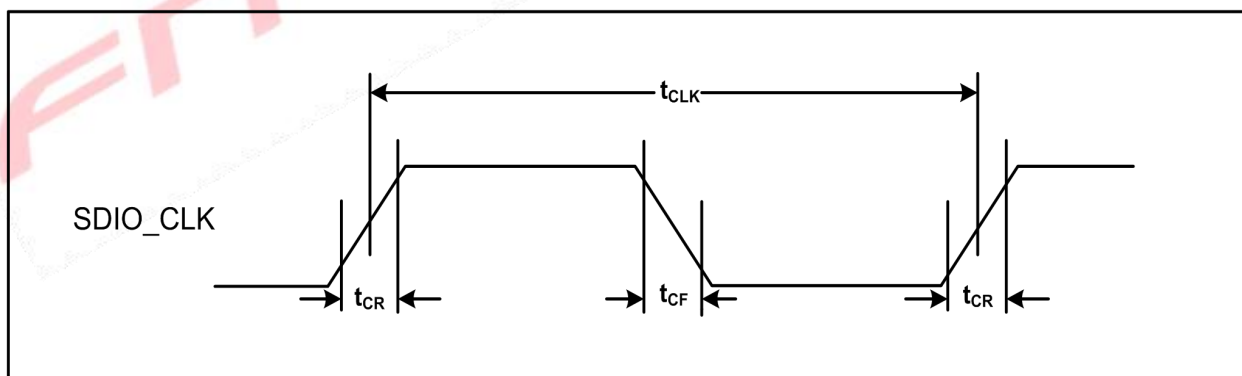
<b>Parameter</b>	<b>Symbol</b>	<b>Minimum</b>	<b>Typical</b>	<b>Maximum</b>	<b>Unit</b>
<b>SDIO CLK(all values are referred to minimum VIH and maximum VIL<sup>b</sup>)</b>					
Frequency - Data Transfer mode	fPP	0	-	50	MHz

Frequency - Identification mode	fOD	0	-	400	kHz
Clock low time	tWL	7	-	-	ns
Clock high time	tWH	7	-	-	ns
Clock rise time	tTLH	-	-	3	ns
Clock low time	tTHL	-	-	3	ns
<b>Inputs:CMD, DAT(referenced to CLK)</b>					
Input setup time	tISU	6	-	-	ns
Input hold time	tIH	2	-	-	ns
<b>Outputs:CMD, DAT(referenced to CLK)</b>					
Output delay time - Data Transfer mode	tODLY	-	-	14	ns
Output delay time - Identification mode	tODLY	2.5	-	-	ns
Total system capacitance(each line)	CL	-	-	40	pF

- a. Timing is based on  $CL \leq 40$  pF load on CMD and Data.
- b.  $Min(V_{ih}) = 0.7 \times VDDIO$  and  $max(V_{il}) = 0.2 \times VDDIO$ .

### 7.2.5 SDIO Bus Timing Specifications in SDR Modes

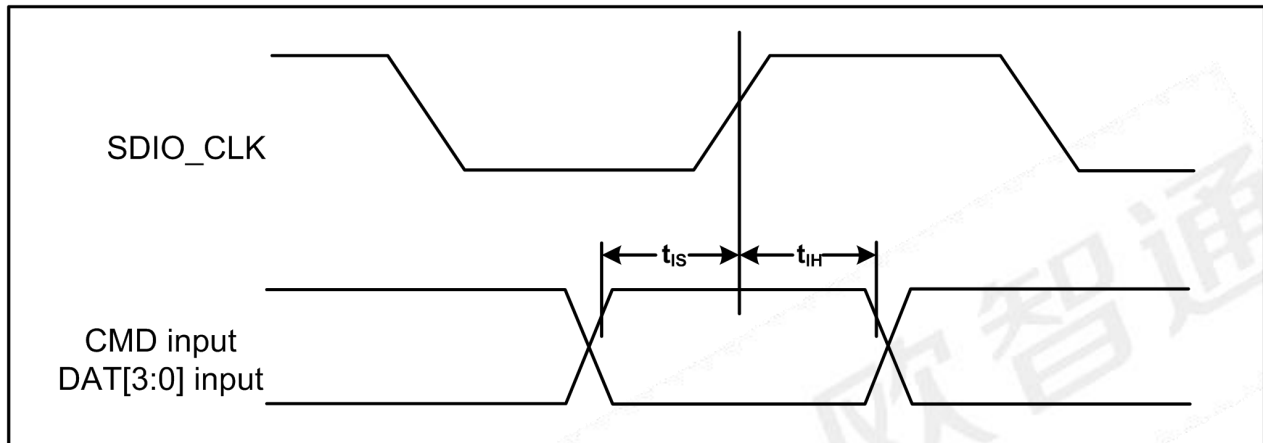
Clock timing (SDR Modes)



Parameter	Symbol	Minimum	Maximum	Unit	Comments
-	t <sub>CLK</sub>	40	-	ns	SDR12 mode
		20	-	ns	SDR25 mode
		10	-	ns	SDR50 mode
		4.8	-	ns	SDR104 mode

-	$t_{CR}, t_{CF}$	-	$0.2 \times t_{CLK}$	ns	$t_{CR}, t_{CF} < 2.00 \text{ ns (max)@100 MHz,}$ $C_{CARD} = 10 \text{ pF}$ $t_{CR}, t_{CF} < 0.96 \text{ ns (max)@208 MHz,}$ $C_{CARD} = 10 \text{ pF}$
Clock duty	-	30	70	%	-

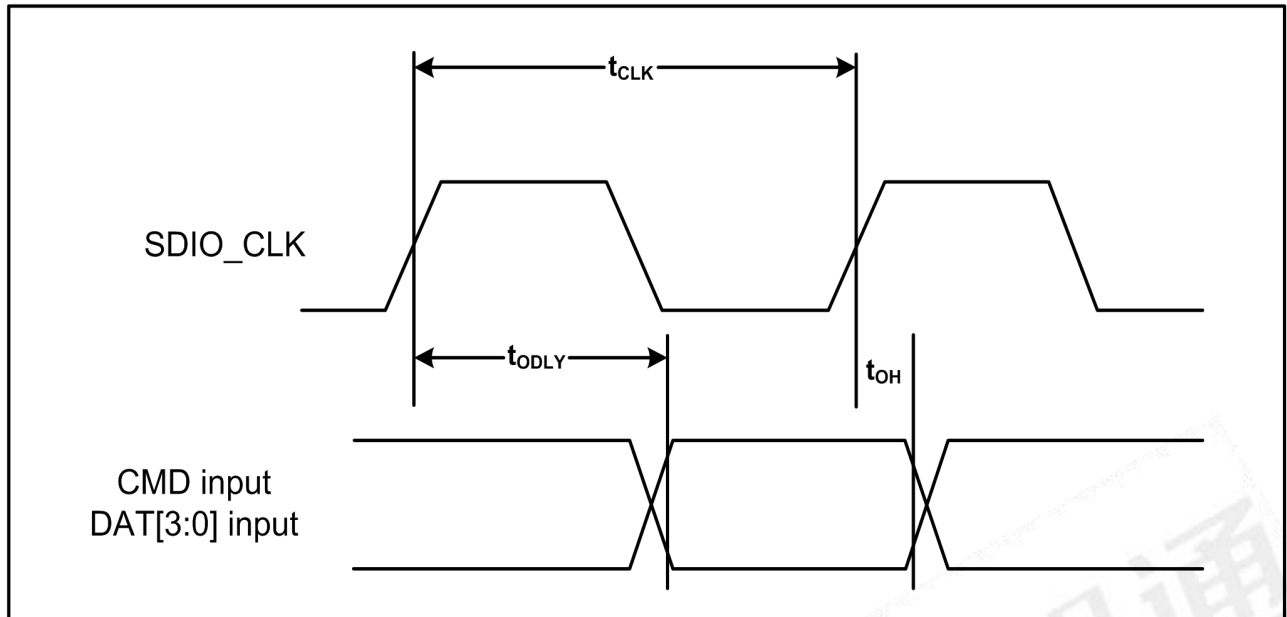
Card Input timing (SDR Modes)



Symbol	Minimum	Maximum	Unit	Comments
<b>SDR104 Mode</b>				
$t_{IS}$	1.70 <sup>a</sup>	-	ns	$C_{CARD} = 10\text{pF, VCT} = 0.975\text{V}$
$t_{IH}$	0.80	-	ns	$C_{CARD} = 5\text{pF, VCT} = 0.975\text{V}$
<b>SDR50 Mode</b>				
$t_{IS}$	3.00	-	ns	$C_{CARD} = 10\text{pF, VCT} = 0.975\text{V}$
$t_{IH}$	0.80	-	ns	$C_{CARD} = 5\text{pF, VCT} = 0.975\text{V}$

a. SDIO 3.0 specification value is 1.40 ns.

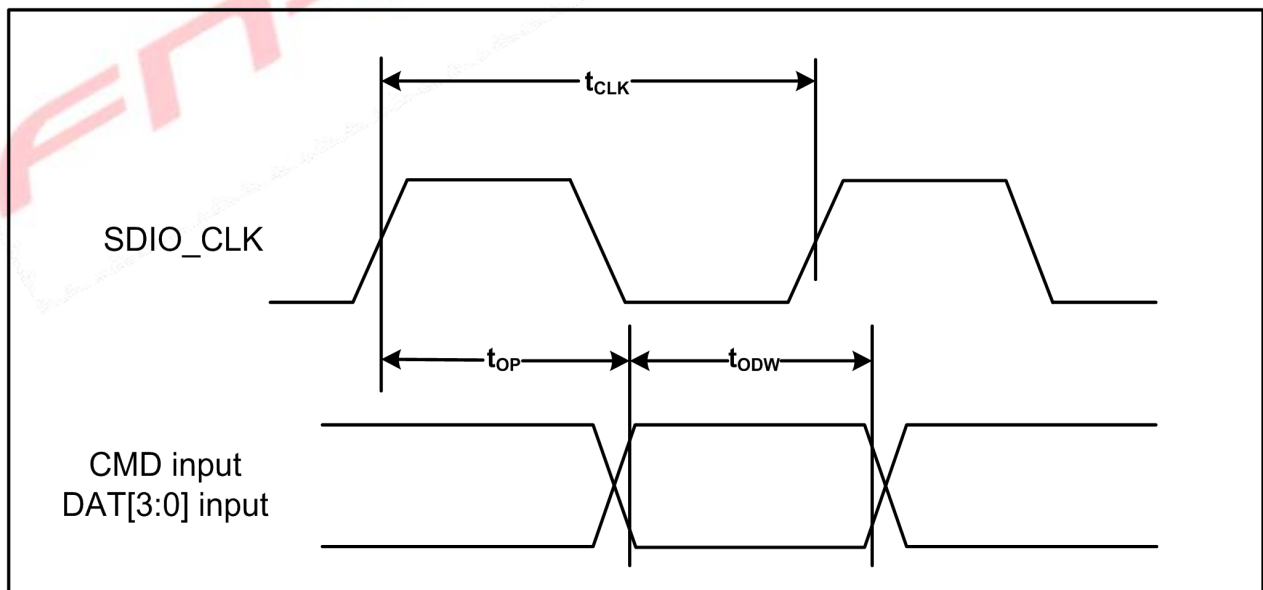
Card output timing (SDR Modes up to 100MHz)



Symbol	Minimum	Maximum	Unit	Comments
t <sub>ODLY</sub>	-	7.85 <sup>a</sup>	ns	t <sub>CLK</sub> ≥ 10 ns C <sub>L</sub> = 30 pF using driver type B for SDR50
t <sub>ODLY</sub>	-	14.0	ns	t <sub>CLK</sub> ≥ 20 ns C <sub>L</sub> = 40 pF using for SDR12, SDR25
t <sub>OH</sub>	1.5	-	ns	Hold time at the t <sub>ODLY</sub> (min) C <sub>L</sub> = 15 pF

a. SDIO 3.0 specification value is 7.5 ns.

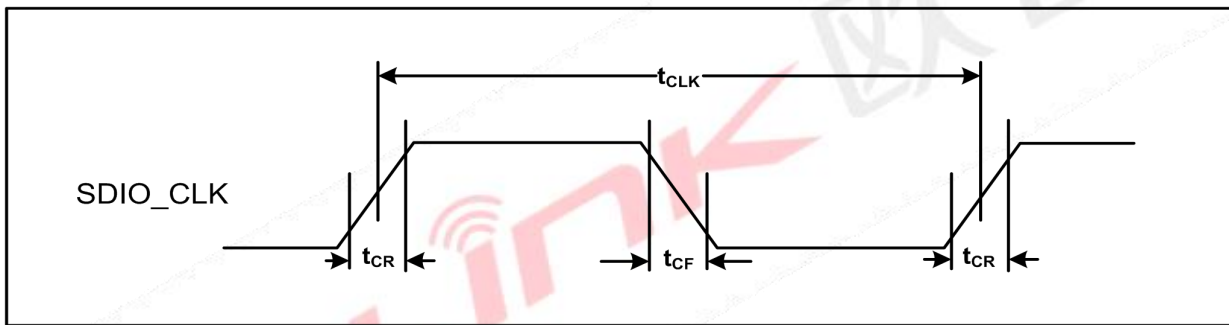
**Card output timing (SDR Modes 100MHz to 208MHz)**



Symbol	Minimum	Maximum	Unit	Comments
$t_{OP}$	0	2	UI	Card output phase
$\Delta t_{OP}$	-350	+1550	ps	Delay variation due to temp change after tuning
$t_{ODW}$	0.6	-	UI	$t_{ODW} = 2.88 \text{ ns @ } 208 \text{ MHz}$

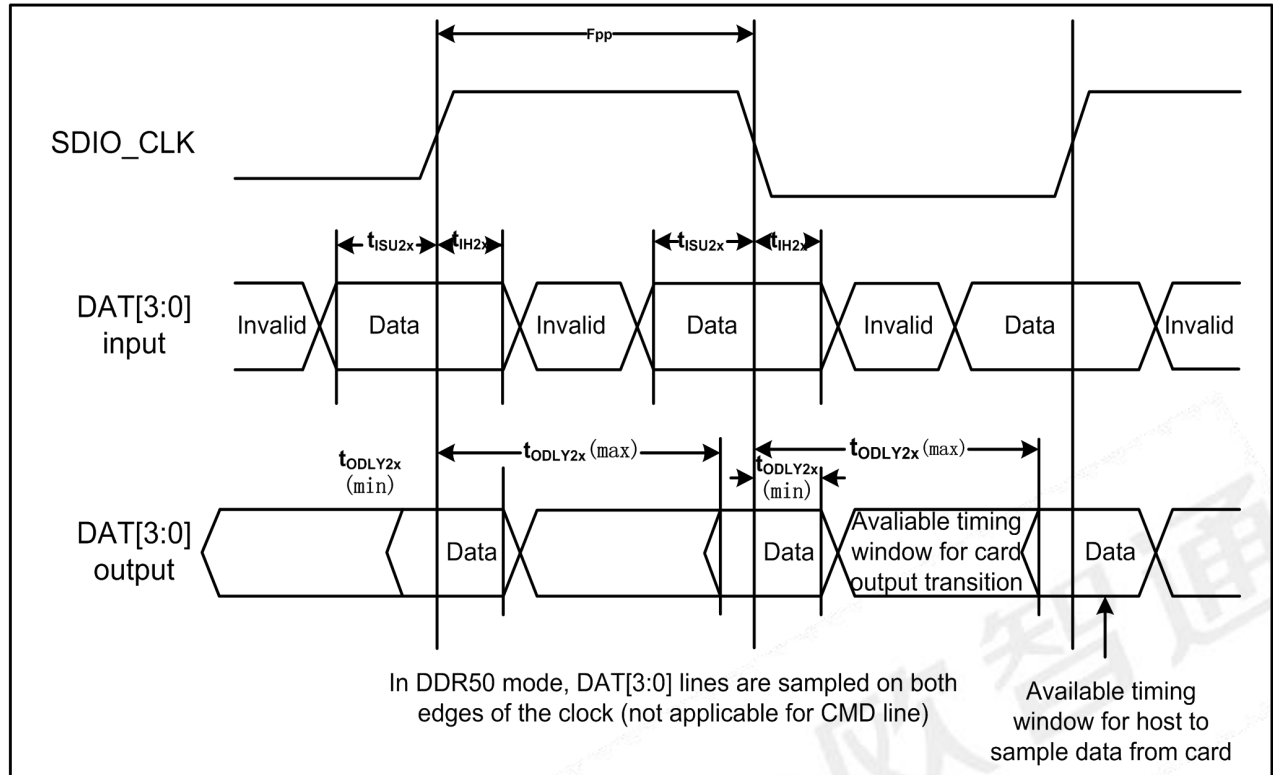
- $\Delta t_{OP} = +1550 \text{ ps}$  for junction temperature of  $\Delta t_{OP} = 90$  degrees during operation
- $\Delta t_{OP} = -350 \text{ ps}$  for junction temperature of  $\Delta t_{OP} = -20$  degrees during operation
- $\Delta t_{OP} = +2600 \text{ ps}$  for junction temperature of  $\Delta t_{OP} = -20$  to  $+125$  degrees during operation

**7.2.6 SDIO Bus Timing Specifications in DDR50 Mode**



parameter	Symbol	Minimum	Maximum	Unit	Comments
-	$t_{CLK}$	20	-	ns	DDR50 mode
-	$t_{CR}, t_{CF}$	-	$0.2 \times t_{CLK}$	ns	$t_{CR}, t_{CF} < 4.00 \text{ ns (max) @ } 50 \text{ MHz, } C_{CARD} = 10 \text{ pF}$
Clock duty	-	45	55	%	-

Data Timing

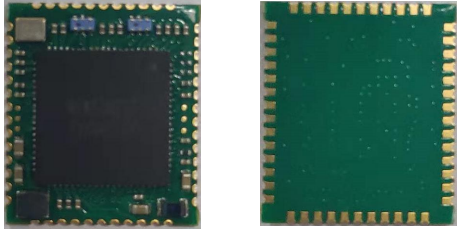
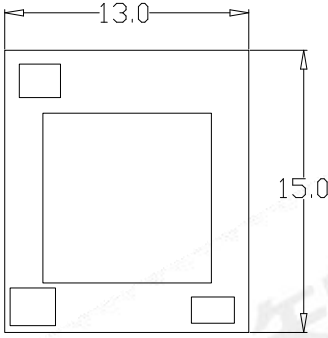
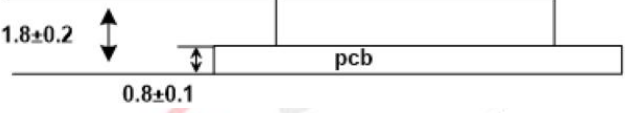


parameter	Symbol	Minimum	Maximum	Unit	Comments
<b>Input CMD</b>					
Input setup time	$t_{ISU}$	6	-	ns	$C_{CARD} < 10$ pF (1 Card)
Input hold time	$t_{IH}$	0.8	-	ns	$C_{CARD} < 10$ pF (1 Card)
<b>Output CMD</b>					
Output delay time	$t_{ODLY}$	-	13.7	ns	$C_{CARD} < 30$ pF (1 Card)
Output hold time	$t_{OH}$	1.5	-	ns	$C_{CARD} < 15$ pF (1 Card)
<b>Input DAT</b>					
Input setup time	$t_{ISU2x}$	3	-	ns	$C_{CARD} < 10$ pF (1 Card)
Input hold time	$t_{IH2x}$	0.8	-	ns	$C_{CARD} < 10$ pF (1 Card)
<b>Output CMD</b>					
Output delay time	$t_{ODLY2x}$	-	7.85 <sup>a</sup>	ns	$C_{CARD} < 25$ pF (1 Card)
Output hold time	$t_{ODLY2x}$	1.5	-	ns	$C_{CARD} < 15$ pF (1 Card)

a. SDIO 3.0 specification value is 7.0 ns

## 8. Size reference

### 8.1 Module Picture

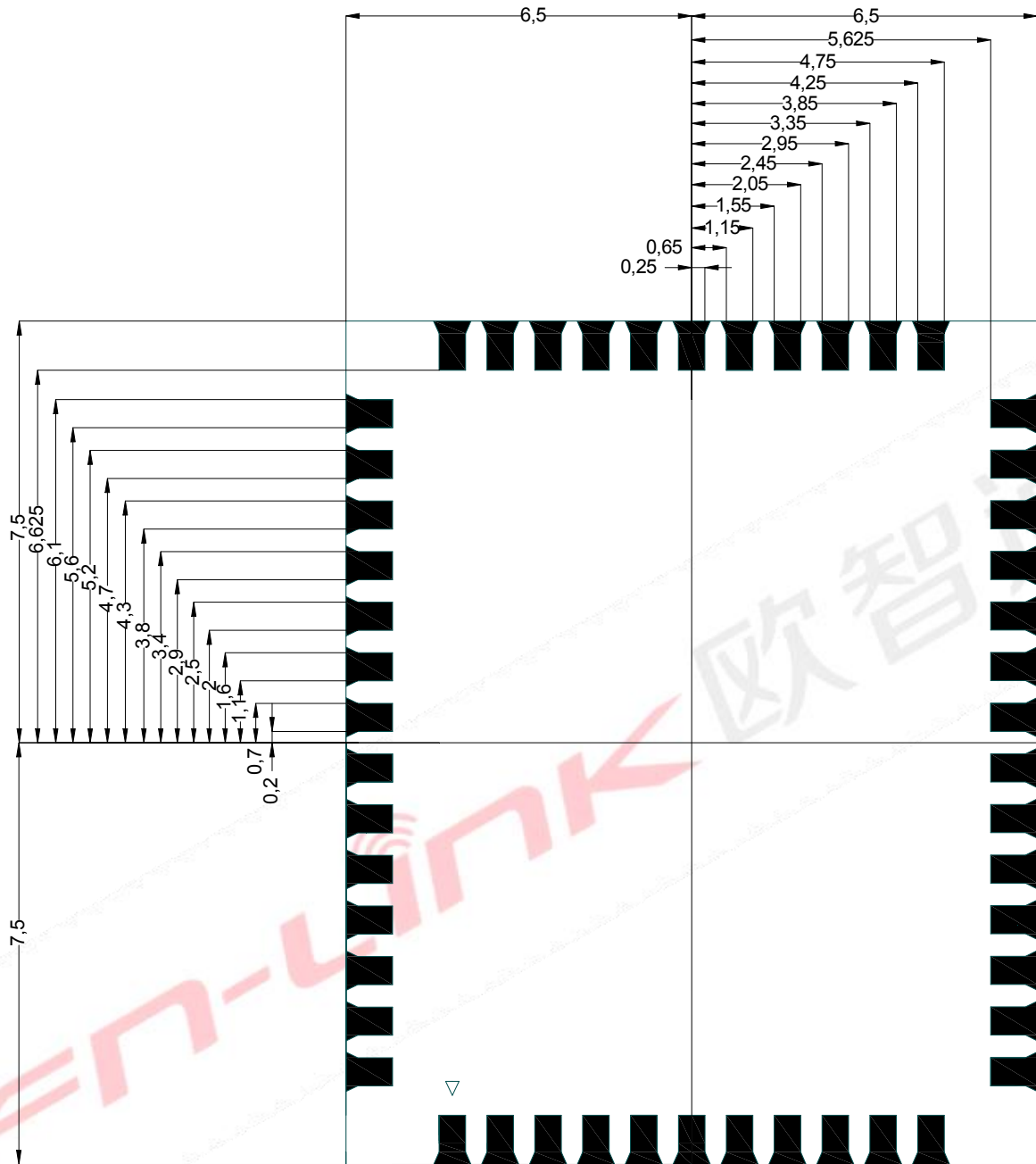
<p><b>L x W : 15 x 13 (+0.3/-0.1) mm</b></p> 	
<p><b>H: 1.8 (±0.2) mm</b></p>	
<p><b>Weight</b></p>	<p>0.67g</p>

### 8.2 Marking Description

NA

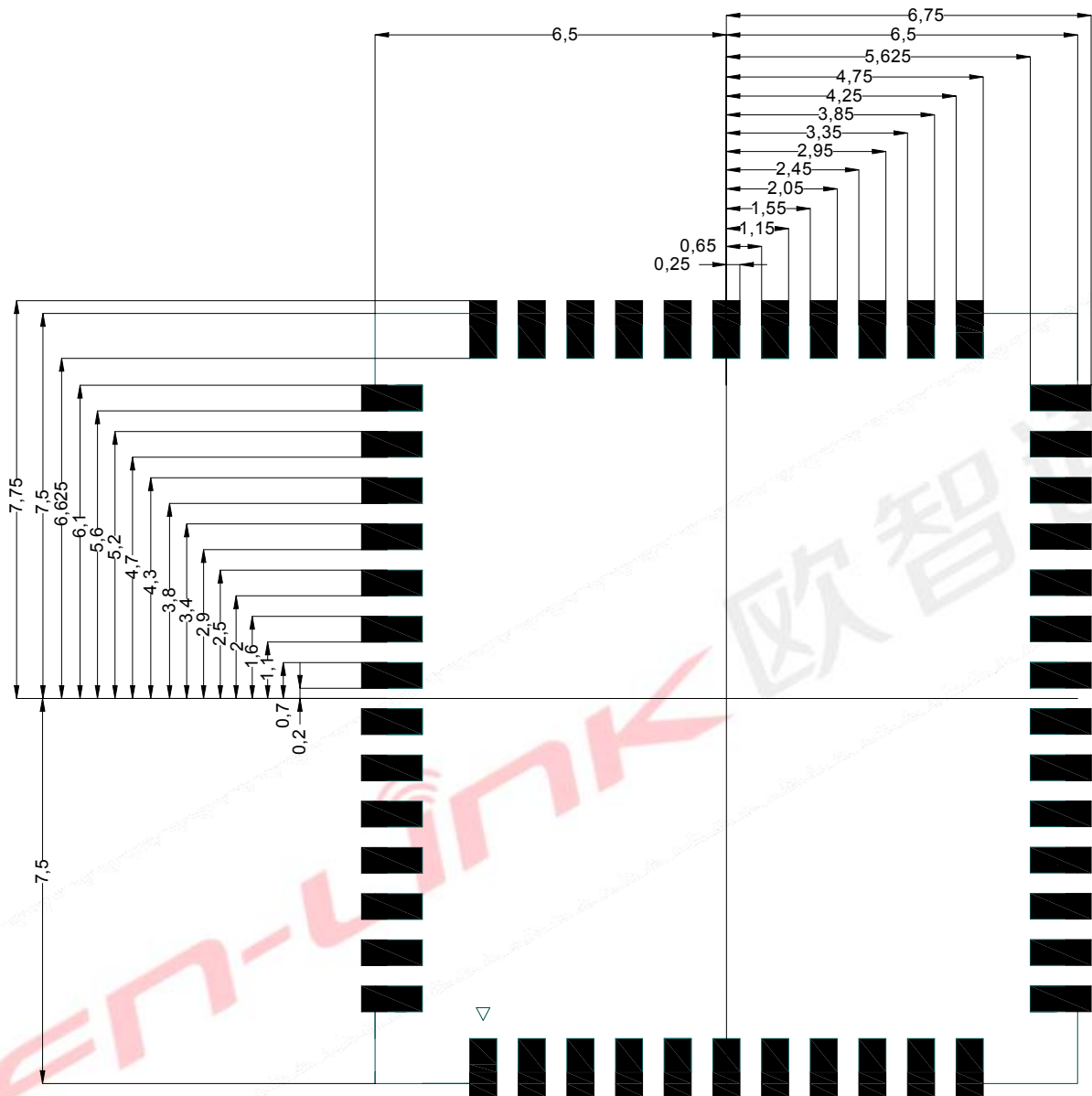
### 8.3 Physical Dimensions

<TOP View>





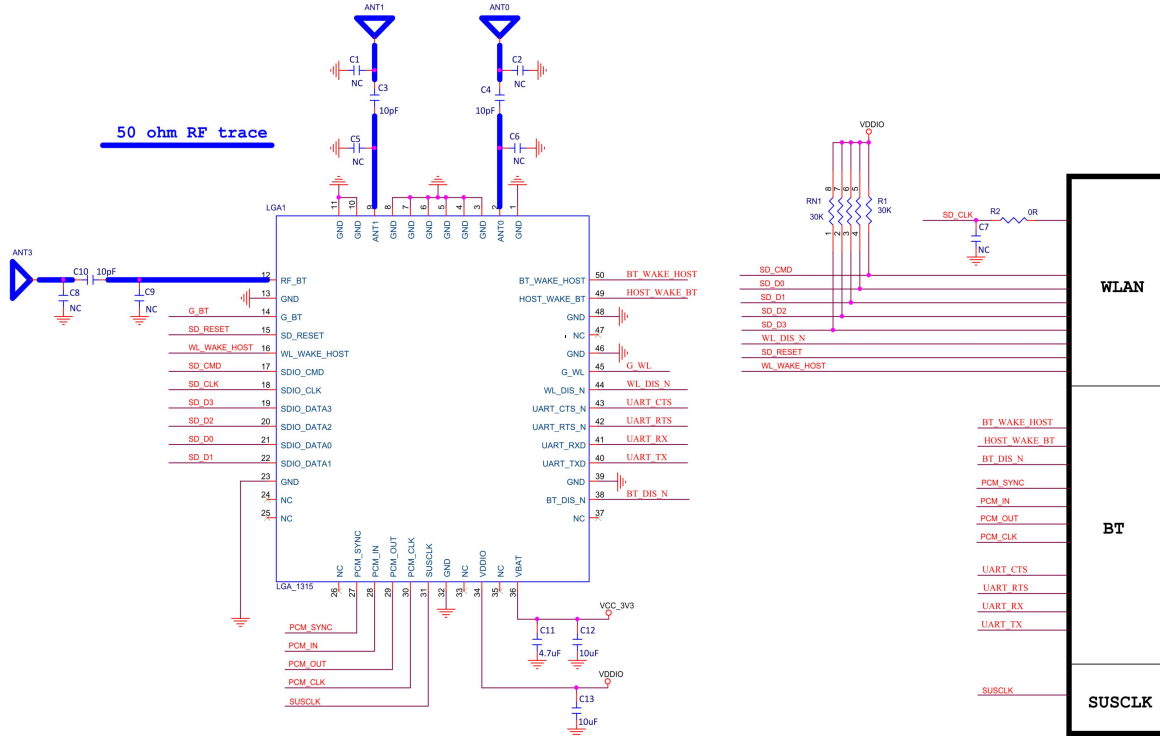
### 8.4 Layout Recommendation



### 9. The Key Material List

Chipset	RTL8852BS-CG	Realtek
PCB	FR4, 4 LAYER, GREEN	XY-PCB, GDKX, Sunlord, SLPCB
Crystal	2016 40MHz	ECEC, TKD, Hosonic, JWT, TXC
Inductor	2016 1.0uH, ±20%	Sunlord, Ceaiya, Cenker
Inductor	0603 2.2UH, ±10%	Sunlord, Ceaiya, Cenker
Diplexer	1608 Dual-band, dual-mode 2.4GHz/5GHz WLAN	Glead, Walsin, ACX, Murata, MAG.LAYERS

# 10. Reference Design



Note:

ANT3 is optional for 3 ANT version

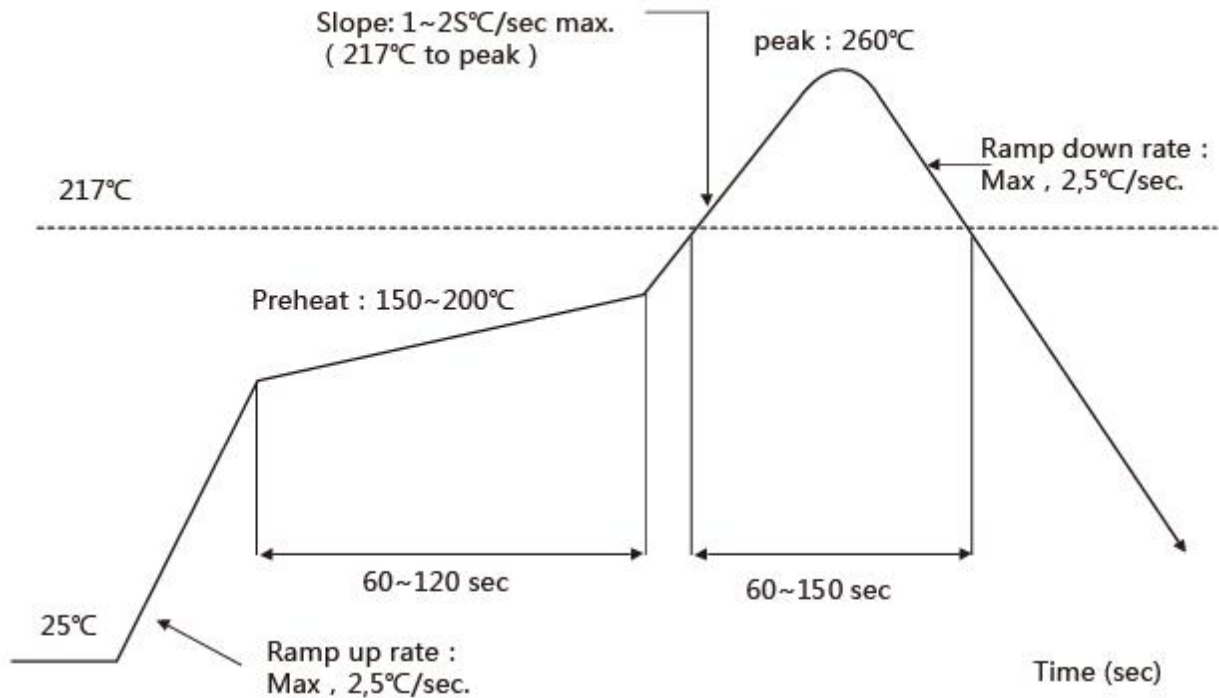
## 11. Recommended Reflow Profile

Referred to IPC/JEDEC standard.

Peak Temperature : <260°C

Time within 5° C of peak temperature: ≥10s

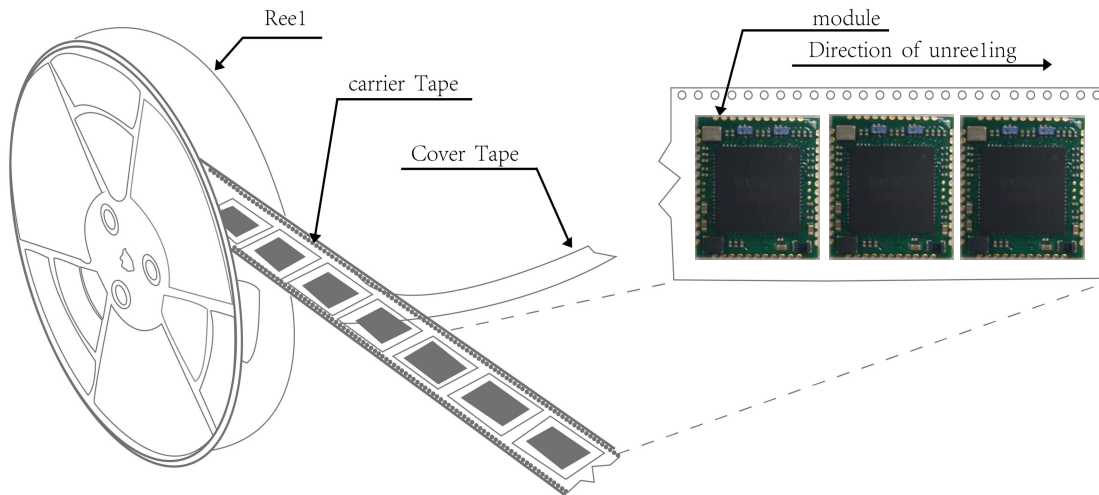
Number of Times : ≤2 times



## 12. Package

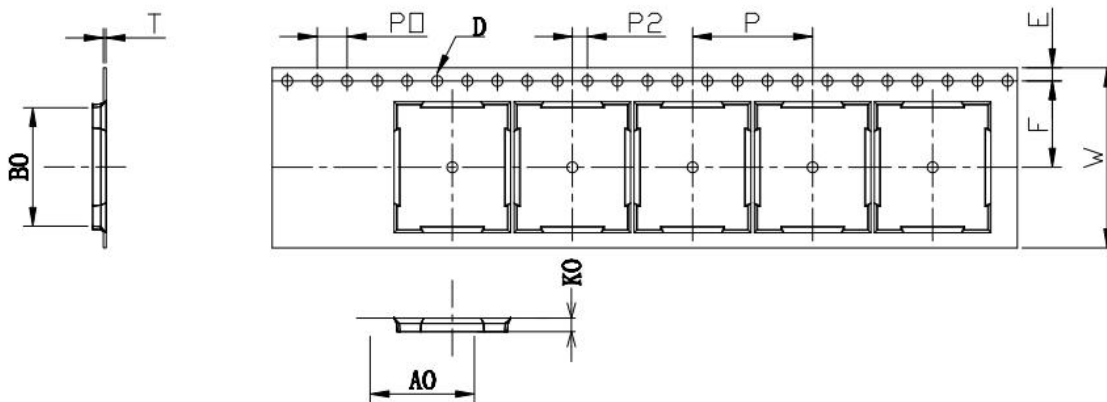
### 12.1 Reel

A roll of 1500pcs



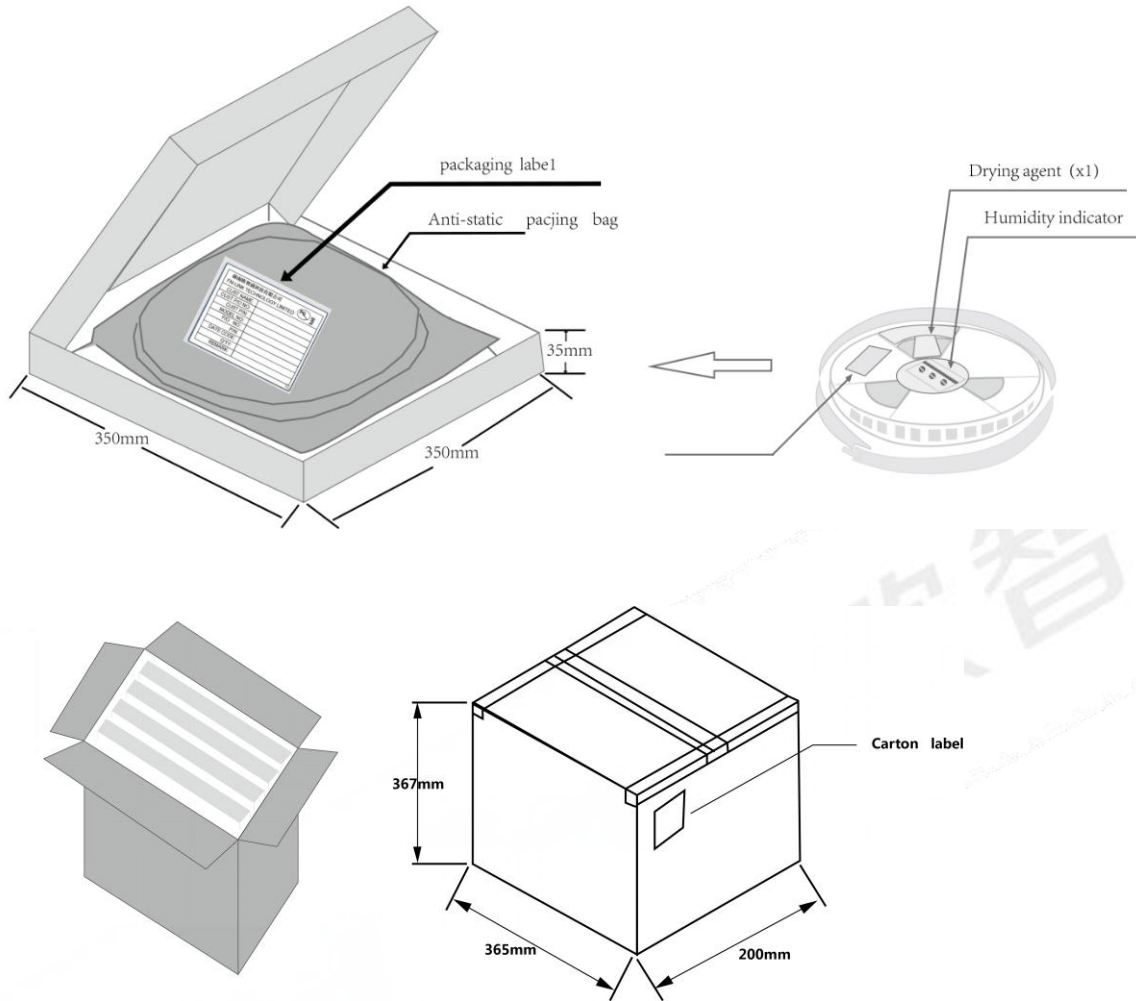
### 12.2 Carrier Tape Detail

ITEM	W	A0	B0	D	F	E	K0	P0	P2	P	T
DIM	24	13.40	15.40	1.50	11.5	1.75	2.65	4.0	2.0	16.0	0.30
TOLE	$\begin{smallmatrix} +0.3 \\ -0.3 \end{smallmatrix}$	$\pm 0.15$	$\pm 0.15$	$\begin{smallmatrix} +0.1 \\ -0.0 \end{smallmatrix}$	$\begin{smallmatrix} +0.1 \\ -0.1 \end{smallmatrix}$	$\pm 0.1$	$\pm 0.10$	$\pm 0.1$	$\pm 0.1$	$\pm 0.1$	$\pm 0.05$



### 12.3 Packaging Detail

the take-up package



### 13. Moisture sensitivity

The Modules is a Moisture Sensitive Device level 3, in according with standard IPC/JEDEC J-STD-020, take care

all the relatives requirements for using this kind of components.

Moreover, the customer has to take care of the following conditions:

- a) Calculated shelf life in sealed bag: 12 months at <math><40^{\circ}\text{C}</math> and <math><90\%</math> relative humidity (RH).
- b) Environmental condition during the production: <math>30^{\circ}\text{C}</math> / 60% RH according to IPC/JEDEC J-STD-033A paragraph 5.
- c) The maximum time between the opening of the sealed bag and the reflow process must be 168 hours if condition
- b) "IPC/JEDEC J-STD-033A paragraph 5.2" is respected

- d) Baking is required if conditions b) or c) are not respected
- e) Baking is required if the humidity indicator inside the bag indicates 10% RH or more

**FN-LINK** 欧智通